

ABSTRACT OF THE DISCLOSURE

Disclosed is a method for manufacturing a composite member comprising a porous substrate, a via, and a wiring. The method comprises exposing a first region and a second region in the porous substrate to a exposure beam through a mask, the second region exposed by the exposure beam not more than 50% of the exposure of the first region, the exposure beam having the wavelength that an average size of voids of the porous substrate is, as expressed by a radius of gyration, $1/20$ to 10 times, and forming the via and the wiring by infiltrating a conductive material into the first region and the second region respectively.